

PCN Number:	20230124000.1	PCN Date:	January 24, 2023
Title:	Qualification of RFAB as an additional Wafer Fab Site option for select C05 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Apr 24, 2023	Sample requests accepted until:	Feb 24, 2023*

***Sample requests received after February 24, 2023 will not be supported.**

Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.

Current Sites			Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DP1DM5	C05	200mm	RFAB	C05	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

Die Rev:

Current	New
Die Rev [2P]	Die Rev [2P]
B	C

Sample product shipping label (not actual product label)

 MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750			(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS
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Product Affected Group:

TAS2505IRGER

TAS2505IRGET

Qualification Report
Approve Date 07-NOVEMBER -2022**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TAS2505IRGER	QBS Reference: PCM5100AQPWRQ1	QBS Reference: TAS2505IRGERQ1	QBS Reference: SH6966ACC0RGCRG4	QBS Reference: TPS2231RGPR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	1/45/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-
HTOL	B1	Life Test	155C	240 Hours	-	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/228/0	3/228/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0	3/228/0
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	-	3/66/0	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	3/15/0
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	-	-

- QBS: Qual By Similarity
- Qual Device TAS2505IRGER is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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